Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

## 2SK2993

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : R_{DS} \, (\text{ON}) = 82 \,\, \text{m}\Omega \, (\text{typ.}) \\ \bullet & \text{High forward transfer admittance} & : | \, Y_{fs} | = 20 \,\, \text{S} \, (\text{typ.}) \\ \bullet & \text{Low leakage current} & : \, I_{DSS} = 100 \,\, \mu\text{A} \, (\text{max}) \, (\text{V}_{DS} = 250 \,\, \text{V}) \\ \bullet & \text{Enhancement-mode} & : \, V_{th} = 1.5 {\sim} 3.5 \,\, \text{V} \, (\text{V}_{DS} = 10 \,\, \text{V}, \, I_{D} = 1 \,\, \text{mA}) \\ \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	250	V	
Drain-gate voltage (Re	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	250	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	20	Α	
	Pulse (Note 1)	$I_{DP}$	60	A 	
Drain power dissipatio	n (Tc = 25°C)	P <sub>D</sub>	100	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	423	mJ	
Avalanche current		I <sub>AR</sub>	20	Α	
Repetitive avalanche	energy (Note 3)	E <sub>AR</sub>	10	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.25	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

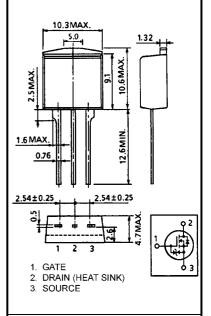
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 1.79 mH,  $I_{AR}$  = 20 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

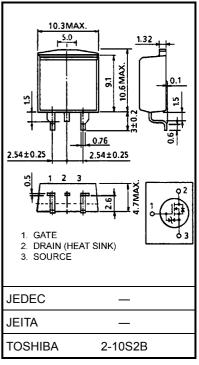
Please handle with caution.



2-10S1B

Weight: 1.5 g (typ.)

JEDEC JEITA TOSHIBA



Weight: 1.5 g (typ.)

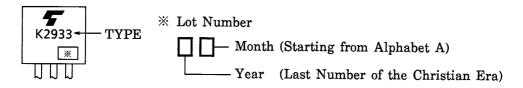
### **Electrical Characteristics (Ta = 25°C)**

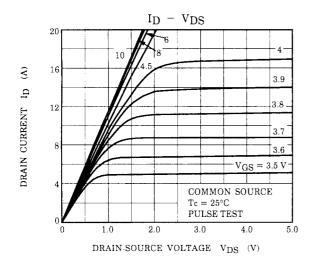
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off cur	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	250	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	٧
Drain-source OI	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A	_	82	105	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A	10	20	_	S
Input capacitano	е	C <sub>iss</sub>		_	4000	_	
Reverse transfer	capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		300	_	pF
Output capacitar	nce	Coss			1000	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10V}{\underset{OV}{\bigcap}} \stackrel{I_{D}=10A}{\underset{RL}{\bigcap}} V_{OUT}$	_	15	_	- ns
	Turn-on time	t <sub>on</sub>		_	35	_	
	Fall time	t <sub>f</sub>		_	30	_	
	Turn-off time	t <sub>off</sub>	$V_{DD} \stackrel{.}{=} 130V$ Duty $\leq 1\%$ , $t_w = 10 \mu s$	_	180	_	
Total gate charg plus gate-drain)	e (gate-source	Qg			100		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	70	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$	<u> </u>		30		

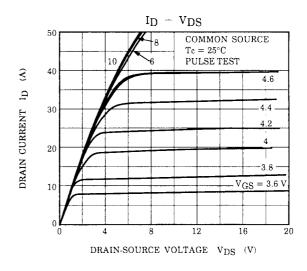
## Source-Drain Ratings and Characteristics (Ta = 25°C)

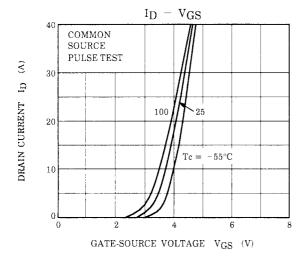
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	-	1	_	20	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>		1		60	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V	_	_	-2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V		300		ns
Reverse recovery charge	$Q_{rr}$	dI <sub>DR</sub> / dt = 100 A / μs		3.3		μC

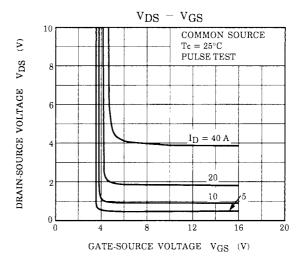
### Marking

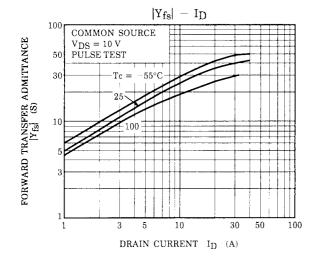


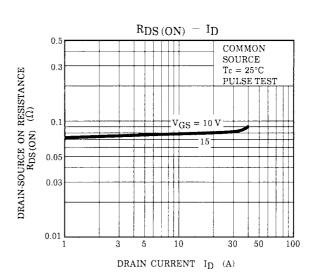


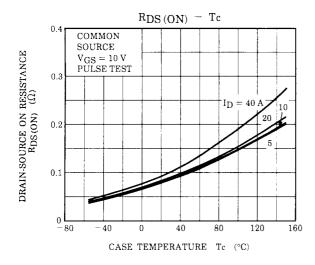


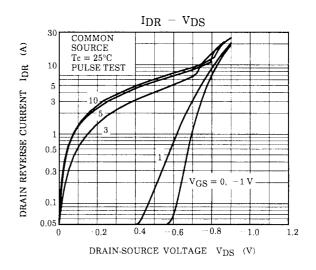


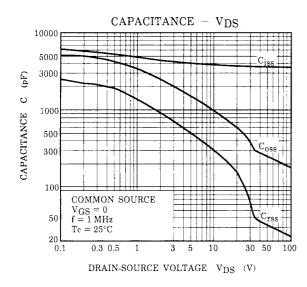


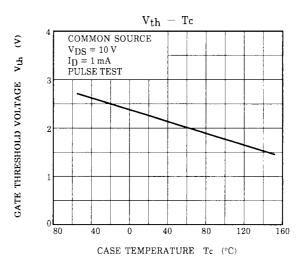


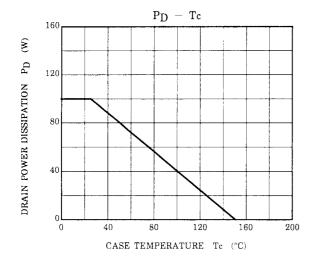


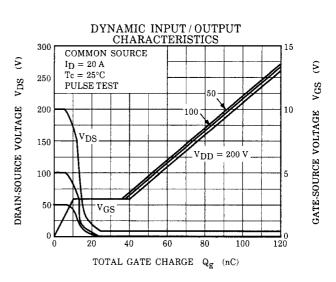




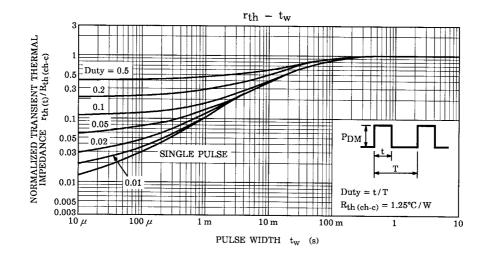


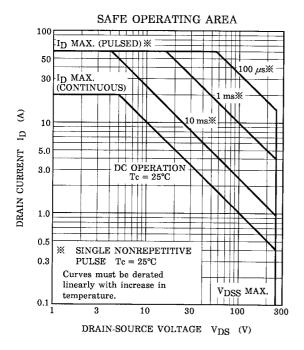


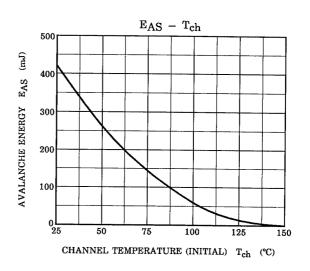


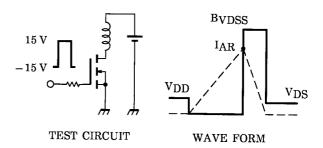


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$$\begin{aligned} &RG = 25~\Omega \\ &V_{DD} = 90~V,~L = 1.79~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BV_{DSS}}{BV_{DSS} - V_{DD}} \right)$$

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